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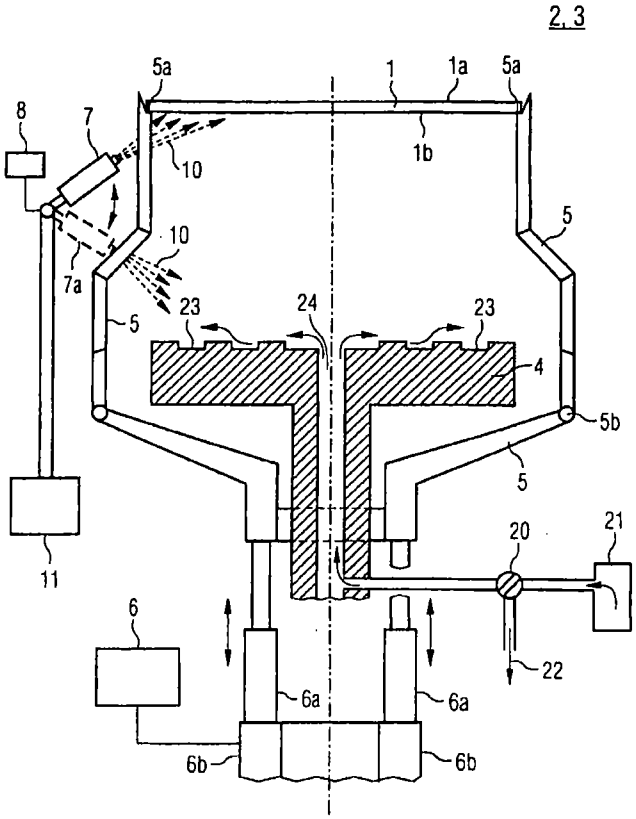
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(54) Title: ARRANGEMENT AND A METHOD FOR REDUCING CONTAMINATION WITH PARTICLES ON A SUBSTRATE IN A PROCESS TOOL



(57) Abstract: A process tool (2), preferrably a spin coater, comprises a set of at least three arms (5) and an adjustable rinse nozzle (7). The arms (5) lift a substrate (1), e.g. a semiconductor wafer, from a chuck (4) inside the process chamber (3) after having performed the corresponding manufacturing step, e.g. coating. The contact area between the arms and the substrate (1) is as small as possible. The rinse nozzle (7) dispenses a solvent liquid (10) onto the backside (1b) of the substrate (1), thereby removing contaminating particles assembling at the position of the contact area of vacuum channels (23) of the chuck (4) with the substrate (1). The set of arms (5) rotates for a homogeneous cleaning. A gas outflow out of vacuum ports (24) of the chuck prevents an obstruction of the vacuum ports (24) with particles. While the substrate (1) is being lifted, the chuck (4) can also be cleaned by dispensing said solvent liquid (10) onto said chuck (4).

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ACTION

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